

AMENDMENT UNDER 37 C.F.R. § 1.111
U.S. Appln. No. 09/538,469

a plurality of capacitor terminals projecting beyond the planar surface of the printed wiring substrate, wherein the respective capacitor terminals are electrically connected to one or the other of the paired electrodes or electrode groups;

the printed wiring substrate comprises a plurality of substrate terminals;

the IC chip comprises a plurality of connection-to-capacitor terminals and a plurality of connection-to-substrate terminals;

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the plurality of capacitor terminals of the capacitor are respectively flip-chip-bonded to a plurality of connection-to-capacitor terminals of the IC chip; and

the plurality of substrate terminals of the printed wiring substrate are respectively flip-chip-bonded to a plurality of connection-to-substrate terminals of the IC chip.

2. (Amended) A printed wiring substrate having a planar surface and a built-in capacitor on which an IC-chip-carrying printed wiring substrate is mounted, characterized in that:

the capacitor comprises:

a pair of electrodes or electrode groups; and

a plurality of capacitor terminals projecting beyond the planar surface of the printed wiring substrate, wherein the respective capacitor terminals are electrically connected to one or the other of the paired electrodes or electrode groups;

the printed wiring substrate comprises a plurality of substrate terminals;

the IC chip-carrying printed wiring circuit comprises a plurality of connection-to-capacitor terminals and a plurality of connection-to-substrate terminals;

A the plurality of capacitor terminals of the capacitor are respectively bonded in a connection-face-to-connection-face manner to a plurality of connection-to-capacitor terminals of the IC-chip-carrying printed wiring substrate; and

the plurality of substrate terminals of the printed wiring substrate are respectively bonded in a connection-face-to-connection-face manner to a plurality of connection-to-substrate terminals of the IC-chip-carrying printed wiring substrate.

A1 4. (Amended) A printed wiring substrate having a planar surface and a built-in capacitor for mounting an IC chip or IC-chip-carrying printed wiring substrate having a plurality of connection-to-capacitor terminals and a plurality of connection-to-substrate terminals, characterized in that:

A2 the capacitor comprises:

a pair of electrodes or electrode groups; and

a plurality of capacitor terminals projecting beyond the planar surface of the printed wiring substrate capable of being respectively flip-chip-bonded or bonded in a connection-face-to-connection-face manner to a plurality of connection-to-capacitor terminals of the IC chip or IC-chip-carrying printed wiring substrate, wherein the respective capacitor terminals are electrically connected to one or the other of the paired electrodes or electrode groups; and

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Q2 the printed wiring substrate comprises a plurality of substrate terminals capable of being respectively flip-chip-bonded or bonded in a connection-face-to-connection-face manner to a plurality of connection-to-substrate terminals of the IC chip or IC-chip-carrying printed wiring substrate.

Please add the following new claims 16-18:

2 16. (New) The printed wiring substrate according to claim 1, characterized in that:

the printed wiring substrate comprises a core substrate made of resin and a capacitor accommodation cavity for accommodating the capacitor; and

the capacitor comprises a dielectric layer made of ceramic and electrodes arranged in alternating layers.

5 17. (New) The printed wiring substrate according to claim *2*, characterized in that:

the printed wiring substrate comprises a core substrate made of resin and a capacitor accommodation cavity for accommodating the capacitor; and

the capacitor comprises a dielectric layer made of ceramic and electrodes arranged in alternating layers.

16 18. (New) The printed wiring substrate according to claim *4*, characterized in that:

the printed wiring substrate comprises a core substrate made of resin and a capacitor accommodation cavity for accommodating the capacitor; and

the capacitor comprises a dielectric layer made of ceramic and electrodes arranged in alternating layers.

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